

Title (en)  
METHOD AND DEVICE FOR WETTING A SUBSTRATE WITH A LIQUID

Title (de)  
VERFAHREN UND VORRICHTUNG ZUM BENETZEN EINES SUBSTRATS MIT EINER FLÜSSIGKEIT

Title (fr)  
PROCEDE ET DISPOSITIF POUR IMPREGNER UN SUBSTRAT AVEC UN LIQUIDE

Publication  
**EP 1606671 A2 20051221 (DE)**

Application  
**EP 04722244 A 20040322**

Priority  
• EP 2004002977 W 20040322  
• DE 10312628 A 20030321

Abstract (en)  
[origin: WO2004082814A2] The invention relates to a method for wetting a substrate with a liquid, said method comprising the following steps: a) a substrate with a surface to be wetted is provided; b) a wetting liquid is provided; c) a protective layer is applied to the substrate, separating the surface to be wetted from the environment; d) the protective layer is structured in order to expose pre-determined wetting areas on the surface of the substrate to be wetted; and e) the wetting liquid is applied to the exposed wetting areas by means of a wetting device without any direct contact between the wetting device and the surface of the substrate to be wetted. The invention also relates to one such mass-produced substrate.

IPC 1-7  
**G03F 7/00**; **H01J 49/04**

IPC 8 full level  
**B01L 99/00** (2010.01); **B05D 1/00** (2006.01); **B05D 1/26** (2006.01); **B05D 1/32** (2006.01); **G03F 1/00** (2012.01); **G03F 7/00** (2006.01); **G03F 7/40** (2006.01); **H01J 49/04** (2006.01)

IPC 8 main group level  
**B01F** (2006.01)

CPC (source: EP US)  
**B01J 19/0046** (2013.01 - EP US); **B01L 3/0293** (2013.01 - EP US); **B82Y 30/00** (2013.01 - EP US); **C40B 50/14** (2013.01 - EP US); **G03F 1/68** (2013.01 - EP US); **G03F 7/40** (2013.01 - EP US); **B01J 2219/00367** (2013.01 - EP US); **B01J 2219/00373** (2013.01 - EP US); **B01J 2219/00378** (2013.01 - EP US); **B01J 2219/00382** (2013.01 - EP US); **B01J 2219/00385** (2013.01 - EP US); **B01J 2219/00387** (2013.01 - EP US); **B01J 2219/00432** (2013.01 - EP US); **B01J 2219/00497** (2013.01 - EP US); **B01J 2219/005** (2013.01 - EP US); **B01J 2219/00527** (2013.01 - EP US); **B01J 2219/00576** (2013.01 - EP US); **B01J 2219/00585** (2013.01 - EP US); **B01J 2219/00596** (2013.01 - EP US); **B01J 2219/00605** (2013.01 - EP US); **B01J 2219/0061** (2013.01 - EP US); **B01J 2219/00612** (2013.01 - EP US); **B01J 2219/00621** (2013.01 - EP US); **B01J 2219/00626** (2013.01 - EP US); **B01J 2219/0063** (2013.01 - EP US); **B01J 2219/00637** (2013.01 - EP US); **B01J 2219/00659** (2013.01 - EP US); **B01J 2219/00675** (2013.01 - EP US); **B01J 2219/00677** (2013.01 - EP US); **B01J 2219/00722** (2013.01 - EP US); **B01J 2219/00725** (2013.01 - EP US); **B01J 2219/00729** (2013.01 - EP US); **B01L 2300/0819** (2013.01 - EP US); **Y10T 428/24802** (2015.01 - EP US); **Y10T 428/31678** (2015.04 - EP US)

Citation (search report)  
See references of WO 2004082814A2

Designated contracting state (EPC)  
AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HU IE IT LI LU MC NL PL PT RO SE SI SK TR

DOCDB simple family (publication)  
**WO 2004082814 A2 20040930**; **WO 2004082814 A3 20050203**; DE 10312628 A1 20041007; EP 1606671 A2 20051221; JP 2006521538 A 20060921; US 2006257630 A1 20061116

DOCDB simple family (application)  
**EP 2004002977 W 20040322**; DE 10312628 A 20030321; EP 04722244 A 20040322; JP 2006500070 A 20040322; US 55047504 A 20040322